

PW3439KDW

20V N-Channel + P-Channel MOSFET

-0.66A -20V; $R_{DS(ON)typ}=450m\Omega@-4.5V$,
 $R_{DS(ON)typ}=650m\Omega@-2.5V, R_{DS(ON)typ}=950m\Omega@-1.8V$.
 0.75A 20V; $R_{DS(ON)typ}=190m\Omega@4.5V$,
 $R_{DS(ON)typ}=260m\Omega@2.5V, R_{DS(ON)typ}=390m\Omega@1.8V$.

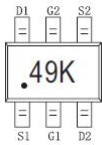
FEATURE

- Surface Mount Package
- Low $R_{DS(on)}$
- Operated at Low Logic Level Gate Drive
- ESD Protected Gate

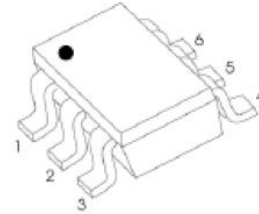
Application

- Load/Power Switching
- Interfacing Switching
- Battery Management for Ultra Small Portable Electronics

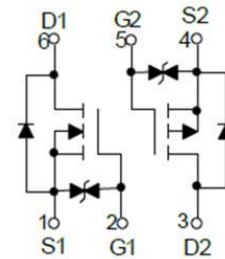
MARKING:



SOT-363



Schematic diagram



ABSOLUTE MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
P-MOSFET			
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current ⁽¹⁾	I _D	-0.66	A
Pulsed Drain Current(tp=10μs)	I _{DM}	-1.2	A
N-MOSFET			
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current ⁽¹⁾	I _D	0.75	A
Pulsed Drain Current(tp=10μs)	I _{DM}	1.8	A
Temperature and Thermal Resistance			
Thermal Resistance from Junction to Ambient ⁽²⁾	R _{θJA}	833	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~ +150	°C
Lead Temperature for Soldering Purposes(1/8" from case for 10s)	T _L	260	°C

P-channel MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-20			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = -20V, V _{GS} = 0V			-1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±10V, V _{DS} = 0V			±20	μA
Gate threshold voltage ⁽²⁾	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-0.35	-0.60	-1.1	V
Drain-source on-resistance ⁽²⁾	R _{DS(on)}	V _{GS} = -4.5V, I _D = -1A		450	580	mΩ
		V _{GS} = -2.5V, I _D = -0.8A		650	840	
		V _{GS} = -1.8V, I _D = -0.5A		950		
Forward tranconductance ⁽²⁾	g _{FS}	V _{DS} = -10V, I _D = -0.54A		1.2		S
Diode forward voltage	V _{DS}	I _S = -0.5A, V _{GS} = 0V			-1.2	V
DYNAMIC CHARACTERISTICS⁽⁴⁾						
Input Capacitance	C _{iss}	V _{DS} = -16V, V _{GS} = 0V, f = 1MHz		113		pF
Output Capacitance	C _{oss}			15		
Reverse Transfer Capacitance	C _{rss}			9		
SWITCHING CHARACTERISTICS^(3,4)						
Turn-on delay time	t _{d(on)}	V _{DS} = -10V, I _D = -200mA, V _{GS} = -4.5V, R _G = 10Ω		9		nS
Turn-on rise time	t _r			5.7		
Turn-off delay time	t _{d(off)}			32.6		
Turn-off fall time	t _f			20.3		

N-channel MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)

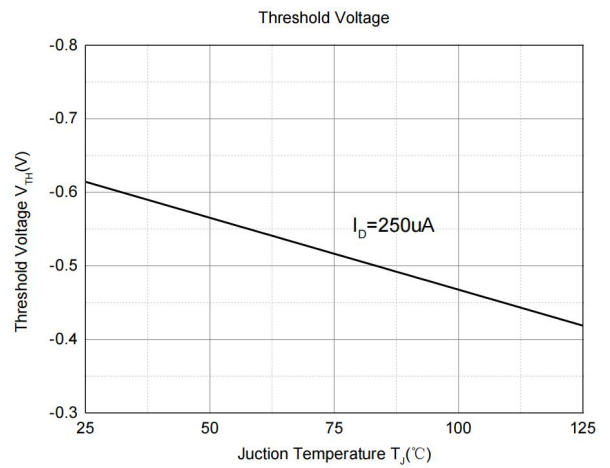
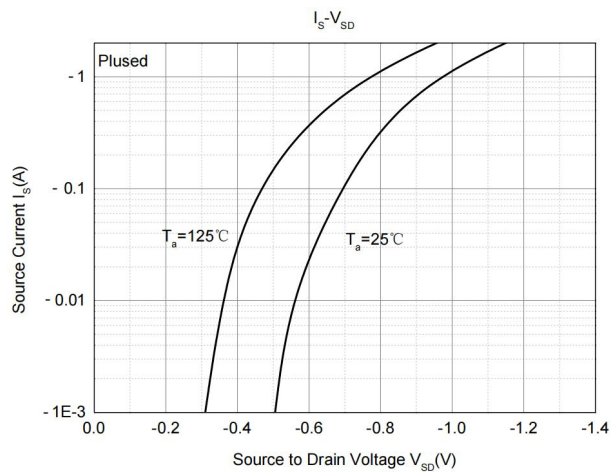
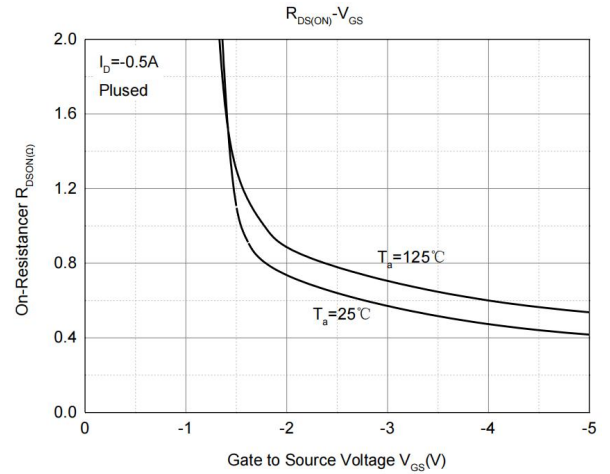
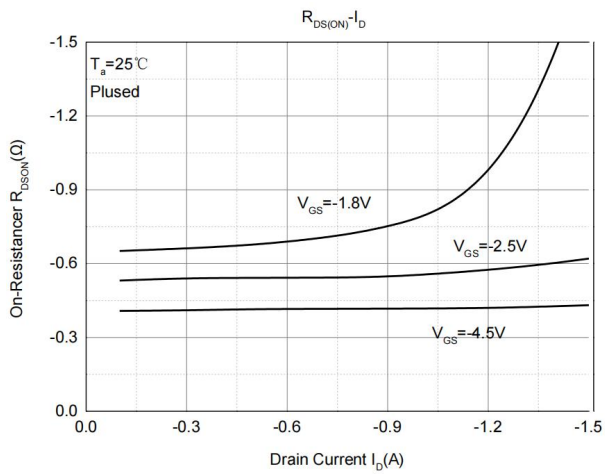
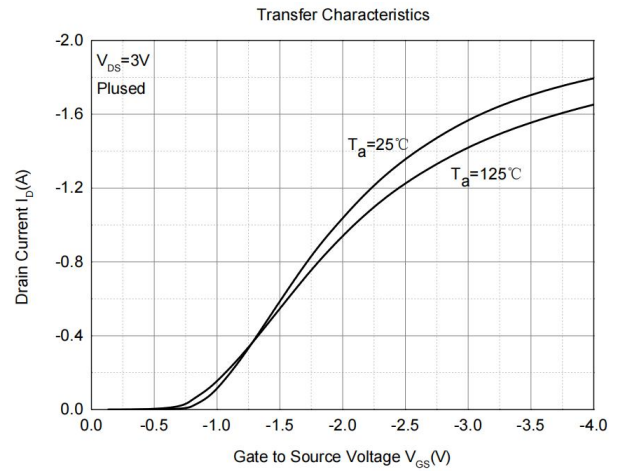
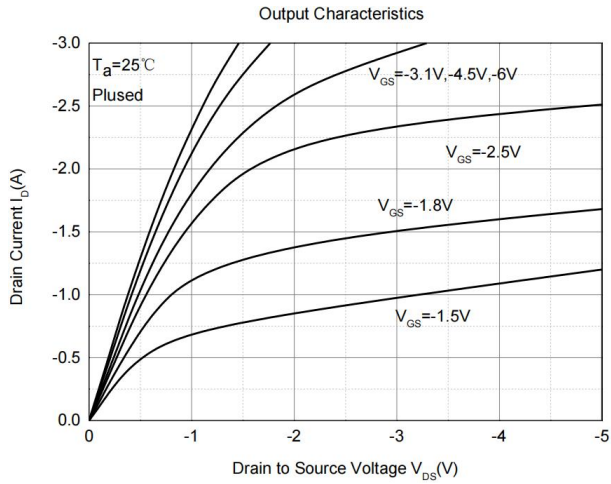
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	20			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =20V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±10V, V _{DS} = 0V			±20	μA
Gate threshold voltage ⁽²⁾	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.35	0.75	1.1	V
Drain-source on-resistance ⁽²⁾	R _{DS(on)}	V _{GS} =4.5V, I _D =650mA		190	260	mΩ
		V _{GS} =2.5V, I _D =550mA		260	360	
		V _{GS} =1.8V, I _D =450mA		390	590	
Forward tranconductance	g _{FS}	V _{DS} =10V, I _D =800mA		1.6		S
Diode forward voltage ⁽³⁾	V _{DS}	I _S =0.15A, V _{GS} = 0V			1.2	V
DYNAMIC CHARACTERISTICS⁽⁴⁾						
Input Capacitance	C _{iss}	V _{DS} =16V, V _{GS} =0V, f=1MHz		79	120	pF
Output Capacitance	C _{oss}			13	20	
Reverse Transfer Capacitance	C _{rss}			9	15	
SWITCHING CHARACTERISTICS^(3,4)						
Turn-on delay time	t _{d(on)}	V _{DS} =10V, I _D =500mA, V _{GS} =4.5V, R _G =10Ω		6.7		nS
Turn-on rise time	t _r			4.8		
Turn-off delay time	t _{d(off)}			17.3		
Turn-off fall time	t _f			7.4		

Notes:

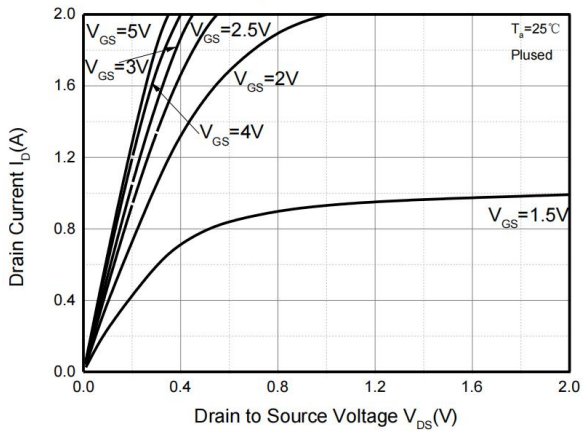
- 1.Surface mounted on FR4 board using the minimum recommended pad size.
- 2.Pulse Test : Pulse Width=300μs, Duty Cycle=2%.
- 3.Switching characteristics are independent of operating junction temperatures.
- 4.Guaranteed by design, not subject to producing.

Typical Electrical and Thermal Characteristics

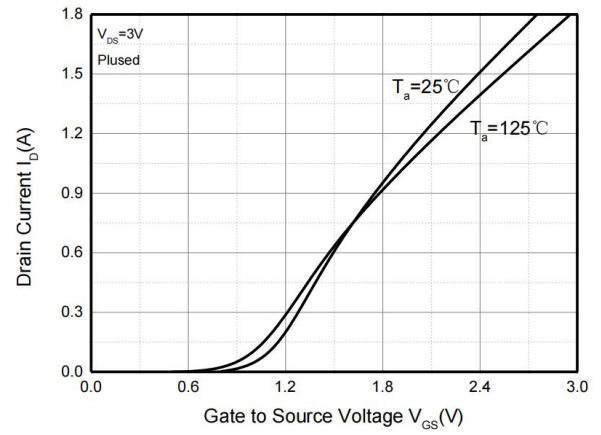
P-Channel MOS



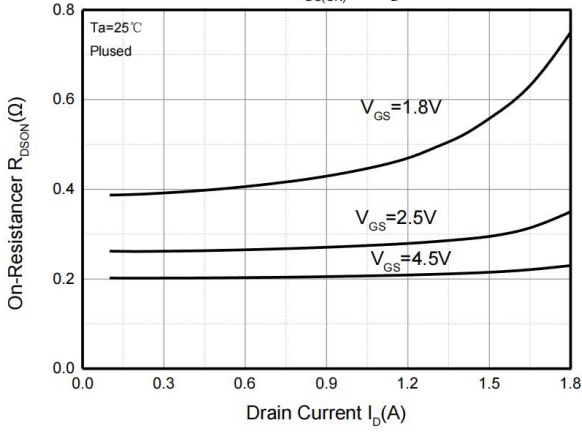
Output Characteristics



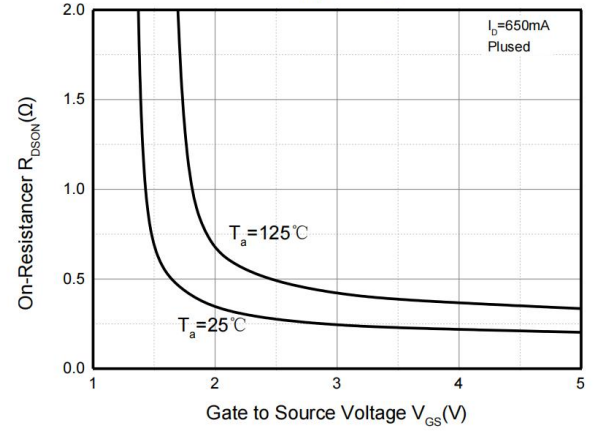
Transfer Characteristics



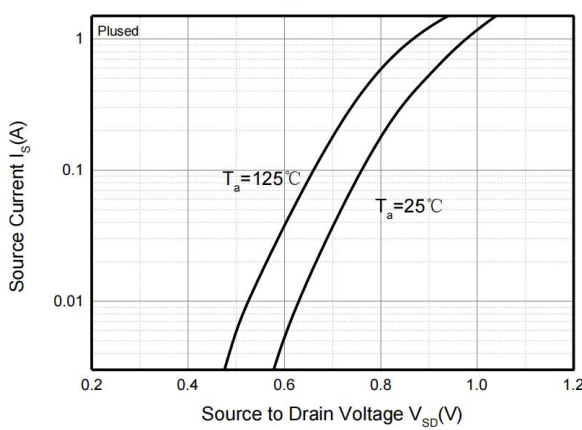
$R_{DS(ON)} - I_D$



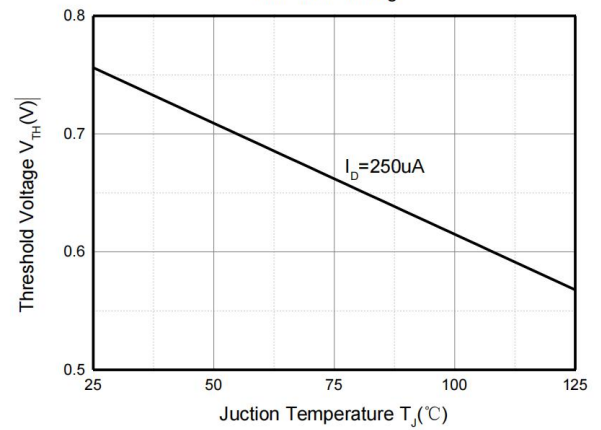
$R_{DS(ON)} - V_{GS}$

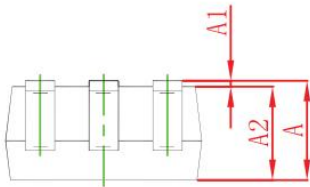
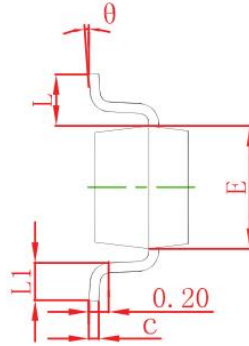
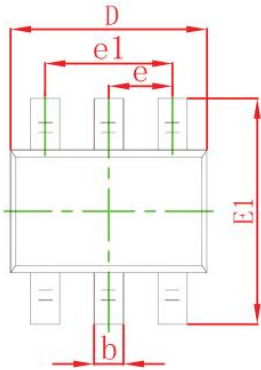


$I_S - V_{SD}$



Threshold Voltage

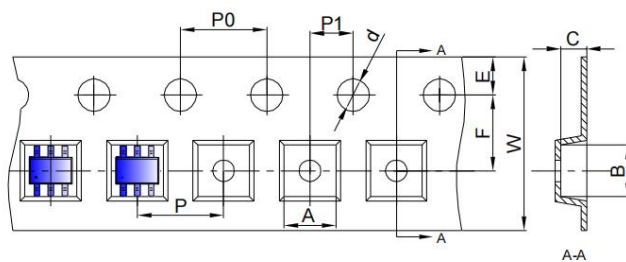




Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

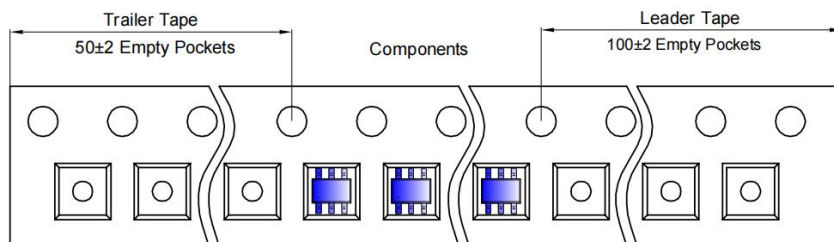
SOT-363 Tape and Reel

SOT-363 Embossed Carrier Tape

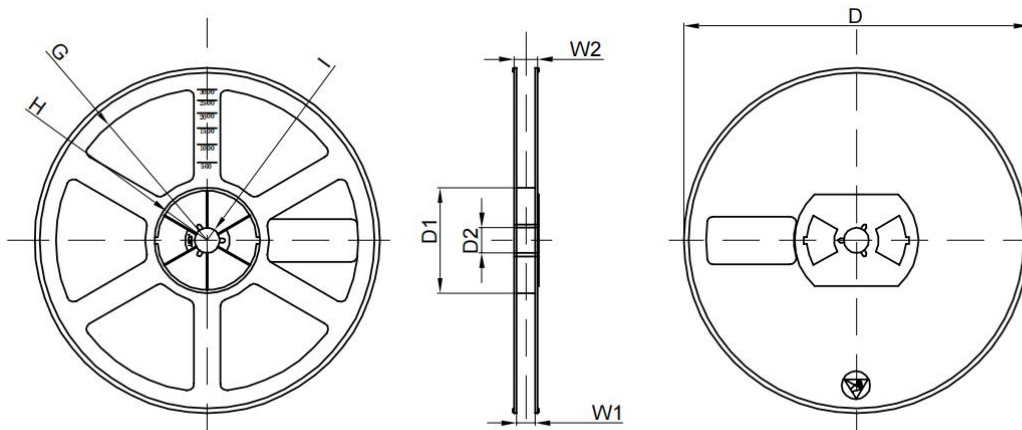


Dimensions are in millimeter										
Pkg type	A	B	C	d	E	F	P0	P	P1	W
SOT-363	2.55	2.55	1.20	Ø1.50	1.75	3.50	4.00	4.00	2.00	12.00

SOT-363 Tape Leader and Trailer



SOT-363 Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
7" Dia	Ø178.00	54.40	13.00	R78.00	R25.60	R6.50	9.50	12.30

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	30,000 pcs	203×203×195	120,000 pcs	438×438×220	